g GE Industrial Control Systems	Test and Operating Procedure	
	DATE : 3/17/2021	PAGE 1 OF 4
QUALITY REP: Robert Dunell		
TITLE: Test Procedure for 531X122PCNxGx card	PROCEDURE: LOU – GED-531X122PCNxGx-B	

1. INTRODUCTORY DESCRIPTION

A. This procedure establishes the methods for testing a 531X121PCNxGx Card.
B. Environmental ranges: 70 +/- 10 Deg. F. with 20-75% R.H.
C. Unit warm-up/stabilization period requirement:
D. Personnel using this procedure are expected to have a high degree of confidence and expertise in related testing and calibration procedures.
E. Procedures not explained here are considered to be understood as common practice.

2. TEST EQUIPMENT VERIFICATION

A. Verify the accuracy of the standard(s) used in the repair/calibration process by evidence of recent calibration labeling affixed to the test equipment.
B. All measurement standards used in this procedure shall be traceable to the NATIONAL INSTITUTE of STANDARDS and TECHNOLOGY (N.I.S.T.) and shall have the accuracy, stability, range and resolution required for the intended use.
C. Unless otherwise specified, the collective uncertainty of the Measurement Standard(s) shall not exceed twenty five percent of the acceptable tolerance for each characteristic being calibrated.
D. All deviations shall be documented.

3. EQUIPMENT CLEANING

A. All equipment clean will be performed as instructed in the GEES SOP Sec. 14.0

4. EQUIPMENT INSPECTION

A. The following criteria should be used as a guideline or basis for the inspection process of the this unit:
    1. Wires broken or cracked.
    2. Terminal strips / connectors broken or cracked.
    3. Loose wires.
    4. Components visually damaged.
    5. Capacitors leaking.
    6. Solder joint, cold.
    7. Circuit board discolored or burned.
    8. Printed wire runs burned or damaged.

5. REVISION HISTORY

Revision	Date	Initials	Reason for Revision
A	02/17/98		Initial Release
B	06/10/02	RKD	Added section 5 & 6
C			
D			
E			
F			
G			
H			
I			
J			
K			

6. REFERENCE DOCUMENTATION

- Reference: GEK
- Factory Procedure #

7. THEORY OF OPERATION

- Reference: GEK85769A or GEJ7301

8. TEST EQUIPMENT TO BE USED

- **Fluke 85 or equivlent**
- **DC-285 test stand**
- **15 HP DC motor**
- **DC-285 test EEPROM Rev A**

9. FINAL TEST AND OPERATION PROCESS

- Control card settings
- JP2 1-2 JP21 1-2 (not on all cards) Switch 9 1 Close 5 Close
- JP5 1-2 JP22 1-2 (not on all cards) 2 Close 6 Close
- JP38 1-2 JP23 1-2(not on all cards) 3 Open 7 Open
- JP19 1-2 JP24 1-2 4 Open 8 Close
- JP20 3-4 JP36 2-3
- JP39 2-3 JP37 2-3 JP40 1-2
- 3TB Settings SW 1 1-Up 2-Up 3-Up 4-Down
- SW 2 1-Up 2-Up 3-Up 4-Up
- Insert DC-285 test EEPROM REV. A U12
- Connect Armature , Field and Tach to test stand
- Push POWER SWITCH on (Located on lower righthand side of test fixture)
- Verify that LED s on Control Card are scrolling from right to left
- If LED s are not a fault has occurred refer GEJ-7301 or GEK-85769 for troubleshooting tips

- Change EEPROM memory location 002 for 128 to 192
- Preform a SCR test by doing the following steps
- Press RESET
- 1. Close SW9-4 (located at bottom-middle of card)
- 2. Push RESET
- 3. Open SW9-4
- 4. Push START
- If SCR Test passed FAULT 42 will be displayed on LED s
- If no faults board tested good
- Change EEPROM memory location 002 for 192 to 128
- If SCR Test failed refer to GEJ-7301 or GEK85769 for troubleshooting tips
- Press RESET

10. SPECIAL INFORMATION

TEST WRITTEN BY: **DATE:** 02/17/98

TEST VERIFIED BY: _____ **DATE:** _____